STANDARD OPERATING PROCEDURE

AJA-TRL
AJA International ATC-1800 sputter deposition system

SYSTEM NOTE:

You must reserve this equipment prior to operating the system. Remember it is mandatory to use CORAL and you must engage the system on CORAL prior to doing any processing. If you are more than 15 minutes late for your reservation you may lose your time slot on this equipment to another user.

INTRODUCTION:

The AJA-TRL is a sputter deposition system is capable of processing samples from small pieces up to 8” diameter wafers. Samples up to 6” in diameter are processed using an aluminum carrier that is loaded into the chamber through a vacuum loadlock. Samples larger than 6” in diameter require manual loading and longer pumpdown times. During deposition, samples will rotate at up to 20rpm (for uniformity) and can be heated by quartz lamps up to 400°C. The sample can also be biased by a 100W RF generator, either for pre-cleaning of the sample or for densification of the film during deposition. The AJA-TRL has 3 deposition sources which accept 3” diameter targets up to 0.25” thick. All 3 sources are normally connected to a 1500W DC generator for depositing conductive materials and can run sequentially. Additionally, one source can be connected to a 600W RF generator to deposit conductive or dielectric materials, or to do co-sputtering with two sources (one DC, one RF). Source 3 is the only source configured for running magnetic materials. Deposition rates can be measured as part of a preliminary conditioning run using a quartz crystal monitor. Most sputtering will be done with Ar gas, but we can do reactive sputtering by adding a low percentage of N₂ or O₂ to the plasma as well.

SAFETY:

In case of a machine emergency, press the Emergency Stop button to power down the tool, and notify a member of the MTL staff. The power supplies on the tool are capable of supplying 1500 watts of DC power or 600W of RF power to the deposition sources. This system is designed with a full array of electrical interlocks that should at no time be defeated or overridden. You should not remove any panels or attempt any repairs on the system.
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PROCEDURE:

You must have a PTC approved process for your sample and film stack in order to use the AJA-TRL. Please check the maintenance section on CORAL to check that the machine is ready to use and to see which targets are currently installed; Ti or Au will normally be installed on the tool, with the 3rd target changing depending on user needs. If you need to deposit a different material, please contact MTL staff to have the necessary target installed. Currently we have Al, Cu, Cr, Ni, Mo, W, and Ag available as additional targets. If you run into problems while running your samples, please put the AJA-TRL into the appropriate state on CORAL (shutdown or problem) and notify MTL staff.

1. Engage the AJA-TRL on CORAL. The CORAL interlock disables the monitor, so you must be engaged in order to operate the software.

Loading your samples

2. Check that the wafer carrier is in the loadlock.
3. Bring the loadlock chamber up to atmosphere by turning off the loadlock pump (Figure 1) and wait until the loadlock pressure gauge (Figure 2) reads greater than 760 Torr (7.6 x 10^2)

![Figure 1 Loadlock pump control](image1)

![Figure 2 Loadlock pressure gauge](image2)
4. Remove the loadlock lid and place it on the 3 rubber pads (Figure 3).
5. Load sample(s) onto the carrier (Figure 4), deposition side up.

6. Replace loadlock lid by tilting the lid so that the edge closest to you is in place, then lower the lid until it is sitting flat on the o-ring.
7. Turn on the loadlock pump and wait for the loadlock pressure gauge to read in the -6 range.

Transferring carrier in

8. Confirm that the loadlock pressure gauge and the chamber ion gauge (Figure 5) are both reading in the -6 range or lower.
9. Open the shutters on both viewports and turn on the lamp.
10. Open the transfer gate valve (Figure 6).

11. Slowly push the transfer arm into the chamber (Figure 7).
12. Make sure the stage is low enough so that the carrier passes over the rotating hub (Figure 8). The pointer underneath the chamber (Figure 9) should be around 30. If the stage is too high, lower it using the stage control joystick (Figure 10).

Figure 8   Stage lowered for transfer
Figure 9   Stage position indicator
Figure 10   Stage control joystick
13. Once the arm is fully inserted, raise the stage so the hub fits into the pocket on the underside of the carrier. Continue raising the stage until the carrier is lifted off the transfer arm and the stage stops moving (Figure 11). The pointer underneath the chamber should be around 40.

![Figure 11  Stage raised to lift carrier](image)

14. Retract the transfer arm.
15. Close the transfer gate valve.
16. Close both viewport shutters and turn off the lamp.

Deposition

17. Lower the stage to process position. This position is marked on the indicator underneath the chamber; the pointer should be around 34.
18. Login to the AJA Phase IIJ software using the password provided during training. Depending on the access level, you will be able to:
   a. Run processes
   b. Edit layers and stacks
   c. Change target configurations
19. Select “Run Process” from the top right part of the screen.
20. Select the stack that you wish to run. If you do not see the stack you want to deposit, contact a staff member to have the proper stack written, or to be trained to write layers and stacks for yourself.
21. If desired, turn data logging on with the appropriate sampling rate.
22. Click open. You will then be asked to verify that all the subsystems are ready to run. The checks you need to make are:
   a. The carrier has been correctly loaded into the chamber and the transfer gate valve is closed.
   b. The chamber ion gauge reads in the low -6 range or lower. If the ion gauge is not on, turn it on with the IG1 switch on the chamber pressure panel.
   c. The VAT pressure controller is in remote mode (Figure 12).

![Figure 12 Chamber pressure controller](image1)

   d. The heater control is in remote mode (Figure 13).

![Figure 13 Substrate heater controller](image2)
e. The DC generator reads “ANLOG” on the front panel (Figure 14).

![DC power supply display](image1.png)

Figure 14  DC power supply display

f. The toggle switch on the stage controller is set to remote (down) and the rotation speed knob is set to 100% (approx 20rpm) (Figure 15).

![Stage position/rotation controller](image2.png)

Figure 15  Stage position/rotation controller

g. The RF generator for the sample bias says “ANALOG” on the front panel (Figure 16).

![Sample bias RF generator](image3.png)

Figure 16  Sample bias RF generator
23. Be sure the carrier is in the chamber (Figure 17). Without the carrier in place, material would be deposited onto the quartz heater window which will reduce heater efficiency and shorten its lifetime. Deposition should never be run without the carrier in the chamber (Figure 18).

24. If all the above conditions are met, press “OK” and the process should start, otherwise press “Cancel”.

25. The process will run through all the cleans and layers that are programmed, then a dialog box will come up saying “Process Complete”.

Unloading

26. Wait for the process chamber pressure to go back into the -6 range.
27. Confirm that the loadlock pressure is in the -6 range or lower.
28. Open the transfer gate valve.
29. Open both shutters and turn on the lamp.
30. Raise the stage to transfer position (pointer should be around 40).
31. Slowly insert the transfer arm.
32. Lower the stage so the hub clears the bottom of the carrier (pointer should be around 32).
33. Slowly retract the transfer arm.
34. Close both shutters and the lamp.
35. Close the transfer gate valve.
36. Turn off the loadlock pump.
37. Wait for the loadlock to come up to atmospheric pressure (7.6x10^2 Torr).
38. Remove the loadlock lid and place it on the three rubber pads.
39. Remove sample(s) from carrier.
40. Replace loadlock lid by tilting the lid so that the edge closest to you is in place, then lower the lid until it is sitting flat on the o-ring.
41. Turn on the loadlock pump and wait for the loadlock pressure gauge to read in the -6 range.
42. Logout of the AJA Phase IIJ software.
43. Disengage the system on CORAL.

If you have any problems or questions, please contact:

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or

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## Appendix A

### Misc info

### QCM Parameters

<table>
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<th>Material</th>
<th>Density</th>
<th>Z-ratio</th>
<th>Film #</th>
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<tr>
<td>Ti</td>
<td>4.5</td>
<td>0.628</td>
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<tr>
<td>Au</td>
<td>19.3</td>
<td>0.381</td>
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<tr>
<td>Al</td>
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<tr>
<td>Cu</td>
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<td>0.437</td>
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<tr>
<td>Cr</td>
<td>7.2</td>
<td>0.305</td>
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<tr>
<td>Ni</td>
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<td>Mo</td>
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<td>W</td>
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<td>Ag</td>
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### Max power density per material

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<td>456</td>
</tr>
<tr>
<td>W</td>
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<td>319</td>
</tr>
</tbody>
</table>

3" round targets: 45.60 cm²